

# **Dual N-Channel 20 V (D-S) MOSFET**

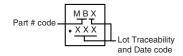
PRODUCT SUMMARY									
V <sub>DS</sub> (V)	20								
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.216								
$R_{DS(on)}(\Omega)$ at $V_{GS} = 2.5 \text{ V}$	0.268								
$R_{DS(on)}(\Omega)$ at $V_{GS} = 1.8 \text{ V}$	0.375								
I <sub>D</sub> (A) <sup>a</sup>	1.5								
Configuration	Dual								

# PowerPAK SC75-6L-Dual

N-Channel MOSFET

N-Channel MOSFET

#### **Marking Code**



#### **FEATURES**

**Definition** 

• High Quality Manufacturing Process Using SMM Process Flow



HALOGEN FREE

• Halogen-free According to IEC 61249-2-21 COMPLIANT

• TrenchFET® Power MOSFET

- New Thermally Enhanced PowerPAK® SC-75 Package
  - Small Footprint Area
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC
- Find out more about Vishay's Medical Products at: www.vishay.com/medical-mosfets

#### **APPLICATION EXAMPLES**

- · Medical Implantable Applications Including
  - Drug Delivery Systems
  - Defibrillators
  - Pacemakers
  - Hearing Aids
  - Other Implantable Devices
- · Load Switch, PA Switch and Battery Switch for Portable **Devices**
- DC/DC Converter

ORDERING INFORMATION	
Package	PowerPAK SC-75
Lead (Pb)-free and Halogen-free	SMMB912DK-T1-GE3

DADAMETED	1	CVMDOL	LINAIT	LINUT	
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub> 20		V	
Gate-Source Voltage		$V_{GS}$	± 8	V	
	T <sub>C</sub> = 25 °C <sup>a</sup>		1.5		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 70 °C <sup>a</sup>		1.5	A	
	T <sub>A</sub> = 25 °C <sup>b, c</sup>	I <sub>D</sub>	1.5		
	T <sub>A</sub> = 70 °C <sup>b, c</sup>		1.4		
Pulsed Drain Current	·	I <sub>DM</sub>	5		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C <sup>a</sup>	1	1.5		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C <sup>b, c</sup>	I <sub>S</sub>	0.9		
	T <sub>C</sub> = 25 °C		3.1	w	
Maximum Dawar Dissipation	T <sub>C</sub> = 70 °C	В	2.0		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C <sup>b, c</sup>	$P_{D}$	1.1	VV	
	T <sub>A</sub> = 70 °C <sup>b, c</sup>		0.7		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 150	°C		
Soldering Recommendations (Peak Temperature)c	-	260	-0		

## SMMB912DK

# Vishay Siliconix



THERMAL RESISTANCE RATINGS									
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT				
Junction-to-Ambient <sup>b, f</sup>	t ≤ 5 s	$R_{thJA}$	90	115	°C/W				
Junction-to-Case (Drain)	Steady State	$R_{thJC}$	32	40					

#### Notes

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c. \ t=5 \ s.$
- d. See Solder Profile (<a href="www.vishay.com/ppg?73257">www.vishay.com/ppg?73257</a>). The PowerPAK SC-75 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions is 125 °C/W.

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static						l	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		20	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			-	22	-	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$		I <sub>D</sub> = 250 μA	-	- 2	-	mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	0.4	-	1	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	= 0 V, V <sub>GS</sub> = ± 8 V	-	-	± 100	nA
Zava Cata Valtaga Drain Current	1	V <sub>GS</sub> = 0 V V <sub>DS</sub> = 20 V		-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 20 V, T <sub>J</sub> = 55 °C	-	-	10	μΑ
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 4.5 V	$V_{DS} \ge 5 V$	5	-	-	Α
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 1.8 A	-	0.180	0.216	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}$	I <sub>D</sub> = 1.6 A	-	0.223	0.268	Ω
		V <sub>GS</sub> = 1.8 V	$I_D = 0.3 \text{ A}$	-	0.300	0.375	
Forward Transconductancea	9 <sub>fs</sub>	V <sub>DS</sub> :	= 10 V, I <sub>D</sub> = 1.8 A	-	3	-	S
Dynamic <sup>b</sup>							
Input Capacitance	$C_{iss}$			-	95	-	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 10 \text{ V}, f = 1 \text{ MHz}$	-	24	-	
Reverse Transfer Capacitance	$C_{rss}$			-	11	-	
Total Gate Charge	$Q_{g}$	$V_{GS} = 8 V$	$V_{DS} = 10 \text{ V}, I_{D} = 1.8 \text{ A}$	-	2	3	
Total date onlinge	Qg			-	1.2	1.8	nC
Gate-Source Charge	$Q_{gs}$	$V_{GS} = 4.5 \text{ V}$	$V_{DS} = 10 \text{ V}, I_{D} = 1.8 \text{ A}$	-	0.3	-	110
Gate-Drain Charge	$Q_{gd}$			-	0.15	-	
Gate Resistance	$R_{g}$		f = 1 MHz	0.5	2.5	5	Ω
Turn-On Delay Time	$t_{d(on)}$			-	5	10	
Rise Time	t <sub>r</sub>		= 10 V, $R_L = 7.1 \Omega$	-	10	20	
Turn-Off Delay Time	$t_{d(off)}$	$I_D \cong 1.4 A$ ,	$V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	24	36	
Fall Time	t <sub>f</sub>			-	8	16	ns
Turn-On Delay Time	$t_{d(on)}$			-	2	4	
Rise Time	t <sub>r</sub>	V <sub>DD</sub> =	-	9	18		
Turn-Off Delay Time	$t_{d(off)}$	I <sub>D</sub> ≅ 1.4 A	-	8	16		
Fall Time	t <sub>f</sub>			-	7	14	
Source-Drain Body Diode Characteristic	s						
Continuous Source-Drain Diode Current <sup>c</sup>	I <sub>S</sub>		-	-	1.5	Α	
Pulse Diode Forward Current	I <sub>SM</sub>				_	5	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> =	1.4 A, V <sub>GS</sub> = 0 V	-	0.7	1.2	V



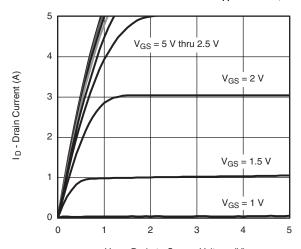
<b>SPECIFICATIONS</b> $T_J = 25$ °C, unless otherwise noted										
PARAMETER	MIN.	TYP.	MAX.	UNIT						
Source-Drain Body Diode Characteristics										
Body Diode Reverse Recovery Time	t <sub>rr</sub>		-	9	18	ns				
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 1.4 A, dl/dt = 100 A/μs, T <sub>.l</sub> = 25 °C	-	3	6	nC				
Reverse Recovery Fall Time	t <sub>a</sub>	$1F = 1.4 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, \text{ fj} = 25 \text{ C}$	-	6	-	no				
Reverse Recovery Rise Time	-	3	-	ns						

#### Notes

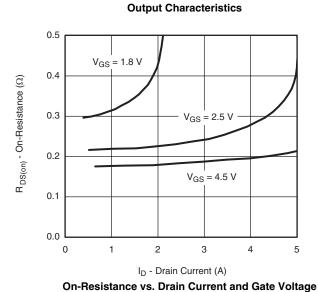
- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Package limited.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

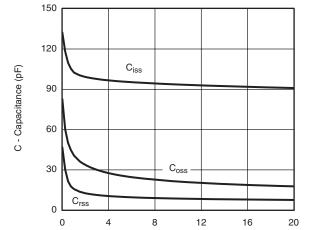
## TYPICAL CHARACTERISTICS T<sub>A</sub> = 25 °C, unless otherwise noted



 $V_{\text{DS}}$  - Drain-to-Source Voltage (V)



V<sub>GS</sub> - Gate-to-Source Voltage (V) **Transfer Characteristics** 

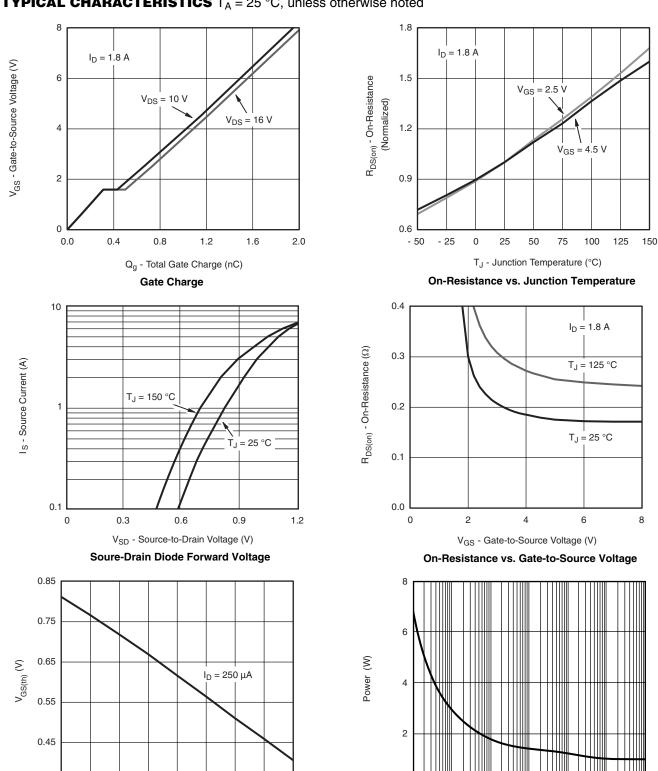


V<sub>DS</sub> - Drain-to-Source Voltage (V)

Capacitance



## **TYPICAL CHARACTERISTICS** $T_A = 25$ °C, unless otherwise noted



0.35 - 50

- 25

75

T<sub>J</sub> - Temperature (°C)

**Threshold Voltage** 

100

125

0.001

0.01

0.1

100

10

Time (s)

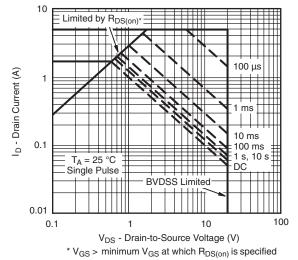
Single Pulse Power, Junction-to-Ambient

1000

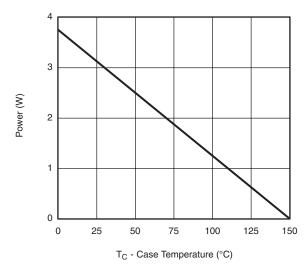




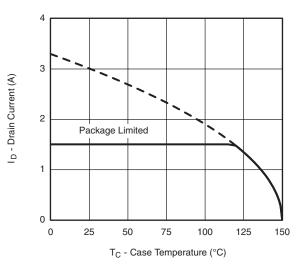
## TYPICAL CHARACTERISTICS T<sub>A</sub> = 25 °C, unless otherwise noted



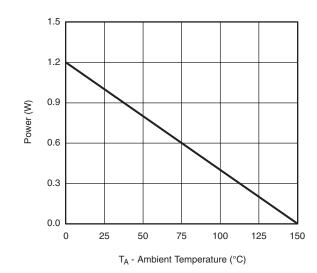
## Safe Operating Area, Junction-to-Ambient



Power Derating, Junction-to-Case



#### **Current Derating\***

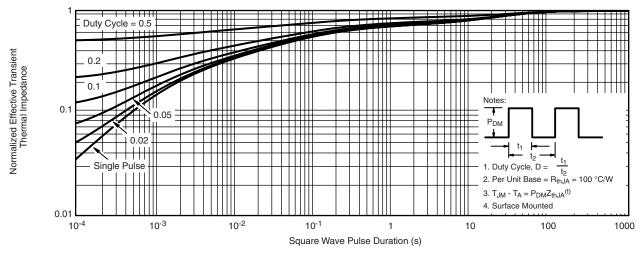


Power Derating, Junction-to-Ambient

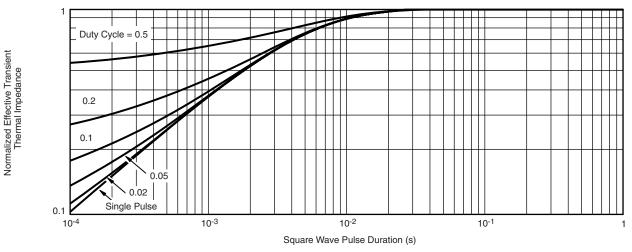
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



## TYPICAL CHARACTERISTICS T<sub>A</sub> = 25 °C, unless otherwise noted



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



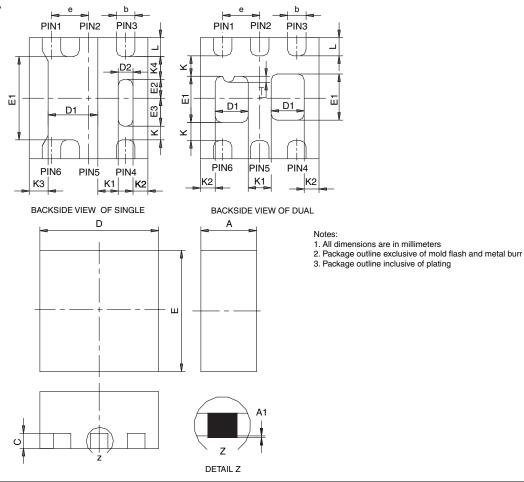
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?65459">www.vishay.com/ppg?65459</a>.





PowerPAK® SC75-6L



			SINGL	E PAD			DUAL PAD					
DIM	M	IILLIMETER	RS		INCHES		MILLIMETERS				INCHES	
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
Α	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032
<b>A</b> 1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002
b	0.18	0.25	0.33	0.007	0.010	0.013	0.18	0.25	0.33	0.007	0.010	0.013
С	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010
D	1.53	1.60	1.70	0.060	0.063	0.067	1.53	1.60	1.70	0.060	0.063	0.067
D1	0.57	0.67	0.77	0.022	0.026	0.030	0.34	0.44	0.54	0.013	0.017	0.021
D2	0.10	0.20	0.30	0.004	0.008	0.012						1
E	1.53	1.60	1.70	0.060	0.063	0.067	1.53	1.60	1.70	0.060	0.063	0.067
E1	1.00	1.10	1.20	0.039	0.043	0.047	0.51	0.61	0.71	0.020	0.024	0.028
E2	0.20	0.25	0.30	0.008	0.010	0.012						1
E3	0.32	0.37	0.42	0.013	0.015	0.017						1
е		0.50 BSC			0.020 BSC	;	0.50 BSC			0.020 BSC		
K		0.180 TYP			0.007 TYP	)	0.245 TYP			0.010 TYP		
K1		0.275 TYP			0.011 TYP	)	0.320 TYP			0.013 TYP		
K2		0.200 TYP			0.008 TYP	)		0.200 BSC			0.008 TYP	
К3		0.255 TYP	1	0.010 TYP								
K4		0.300 TYP			0.012 TYP							
L	0.15	0.25	0.35	0.006	0.010	0.014	0.15	0.25	0.35	0.006	0.010	0.014
Т							0.03	0.08	0.13	0.001	0.003	0.005
ECN: C-	07/31 Re	v C 06-Au	g_07	1								

ECN: C-07431 - Rev. C, 06-Aug-07

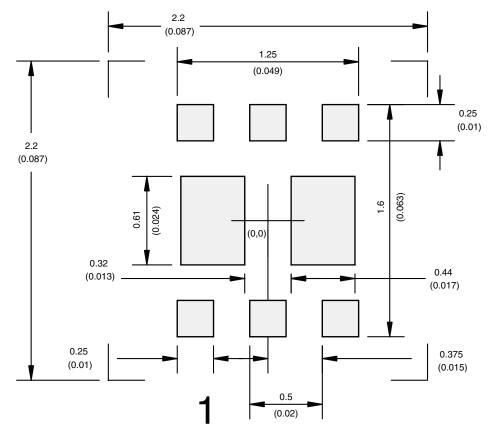
DWG: 5935

Document Number: 73000 06-Aug-07

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## RECOMMENDED PAD LAYOUT FOR PowerPAK® SC75-6L Dual



Dimensions in mm/(Inches)

Return to Index

APPLICATION NOTE



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Vishay

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